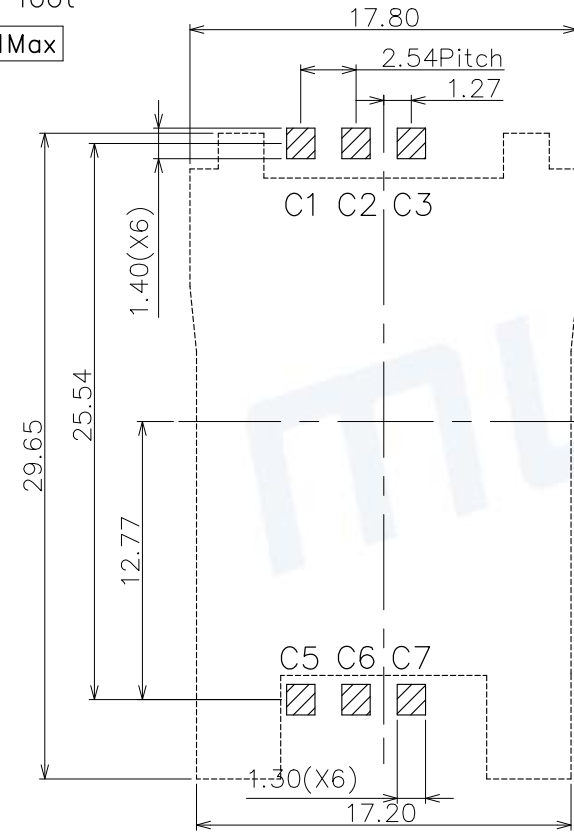
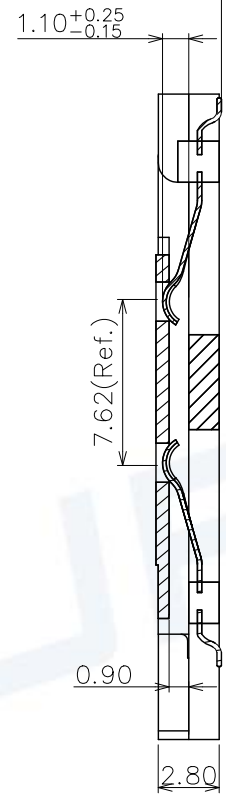
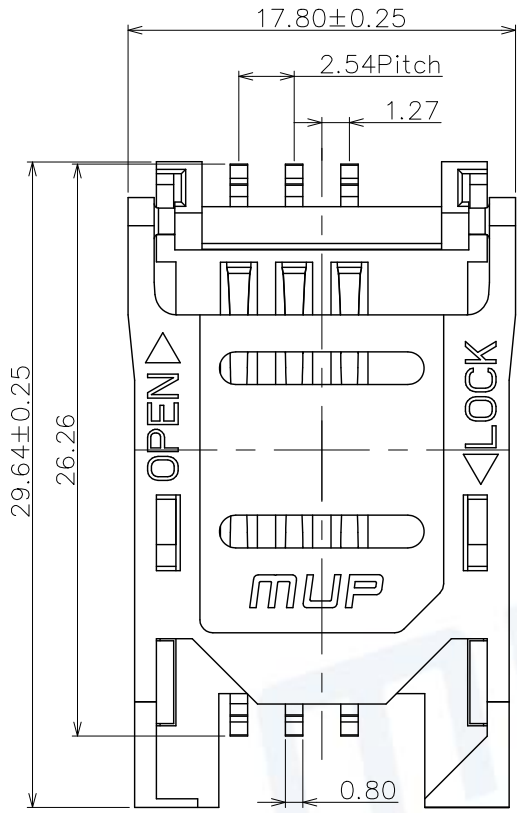


REV.	DESCRIPTION OF REVISIONS	APPR.	CHKD.	DRAW.	DATE
△	新开			Zoey	2006.3.10
△	增加主体塑性变形尺寸			huabo	2020.9.17
△	Original Model C713-23			huabo	2023.10.26

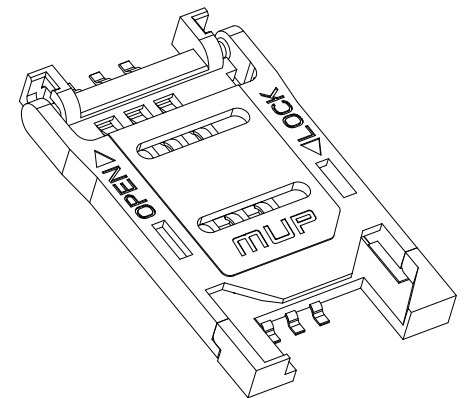
Flatness of solder foot

0.1Max

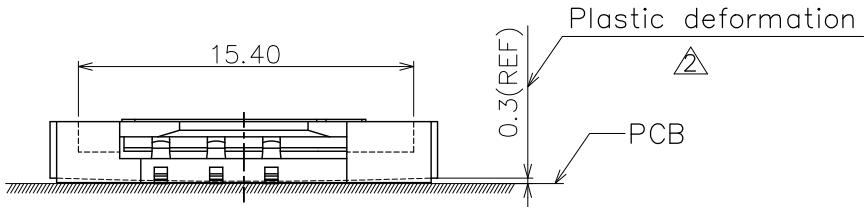


TECHNICAL CHARACTERISTICS

- General Characteristics
Durability: 5,000 cycles min.
- Electrical Characteristics
Contact resistance: Initial: 50mΩ Max.
After Test: 100mΩ Max.
Insulation resistance: >1000MΩ/500V DC
- Solderability
IR reflow: 250°C, 5sec. Max
Manual soldering: 370°C, 3sec. Max
- Environmental Characteristics
Operating temperature: -40°C ~ +85°C
Operating humidity: 10% ~ +95%RH



RECOMMENDED P.C.B LAYOUT
COMPONENT SIDE (TOLERANCE ±0.05)



ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	BASE	1	Hi-temp Thermoplastic	Natural color UL94V-0
2	COVER	1	Hi-temp Thermoplastic	Natural color UL94V-0
3	DATA CONTACT	6	Copper Alloy	Contact area: 15u" Au plated

Unless otherwise specified, other tolerance are:

X	±0.35	X'	±5'
X.X	±0.25	X.X'	±4'
X.XX	±0.15	X.XX'	±3'
X.XXX	±0.10	X.XXX'	±2'

MUP MUP INDUSTRIAL CO.,LTD.

NAME: **SIM Card Connector**

MODEL NO: **MUP-C7013-23**

TYPE: **H2.8 without post 6p**

PROJ.	UNIT	SCALE	DRAWN	Zoey Mar.10.2006	DWG NO.:
①	mm	1:1	CHECKED	Jimmy Mar.10.2006	DWG-C7013-23-01
CUSTOMER DRAWING			APPROVAL	Simon Mar.10.2006	SHEET
					1/1
					REVISION
					3

